

4 Leads - DMPS
Package Material Declaration



Date	14-Dec-17	Product name	Integrated Circuit
Package Code	VS	RoHS Compliant	Y
Package Name	Dual Mold package with straight leads	Halogen Free	Y
Product Total Mass (g)	0.25189	Plating	Pure Matte Sn
Product Number	MLX90364		

Material Declaration

Part Name	Material Name	Component Weight (g)	Material Component (Element)	CAS #	Element ratio (%)	Material Weight (g)	Ratio total Wt (ppm)		
Leadframe	K75 (C18070)	0.11096	Copper (Cu)	7440-50-8	99.75	0.11069	439429		
			Chromium (Cr)	7440-47-3	0.20	0.00022	881		
			Silicon (Si)	7440-21-3	0.03	0.00003	132		
			Titanium (Ti)	7440-32-6	0.02	0.00002	88		
Frame plating	Ag plating	0.00120	Silver (Ag)	7440-22-4	100	0.00120	4764		
Die	Silicon IC	0.00351	Silicon (Si)	7440-21-3	99.99	0.00351	13933		
			Misc.	-	0.01	0.0000004	1		
IMC	S-FeNi-8	0.000006	Iron (Fe)	7439-89-6	19.75	0.0000012	5		
			Nickel (Ni) (0.0 ~ 80%)	7440-02-0	40	0.0000024	10		
			Molybdenum (Mo) (0.0 ~ 80%)	7439-98-7	40	0.0000024	10		
			others (max. 0.5%)	-	0.25	0.00000002	0.1		
Die attach materials	Silver / Epoxy Adhesive CRM1076WB	0.00095	Silver (Ag)	7440-22-4	80	0.00076	3005		
			Epoxy Resin A	9003-36-5	15	0.00014	563		
			Misc.	-	5	0.00005	188		
Capacitor (3x)	Ceramic element (ZB)	Ceramics	0.01308	Barium oxide, obtained by calcinin	1304-28-5	60	0.00785	31150	
				Titanium dioxide	13463-67-7	30	0.00392	15575	
				Misc.	-	10	0.00131	5192	
	Inner electrode (ZD)	Nickel/Other Nickel alloy	0.002058	Nickel (Ni)	7440-02-0	100	0.00206	8170	
									Outer electrode (ZF)
	Glass	0.00021	Palladium (Pd)	7440-05-3	30	0.00057	2258		
			Outer electrode (ZG)	Copper	0.001494	Glass w/o declarable substances	7631-86-9	99	0.00021
	Glass	0.000165				Misc.	-	1	0.00000
							Copper (Cu)	7440-50-8	100
	Glass w/o declarable substances	7631-86-9					99	0.00016	649
Capacitor attach materials	Silver / Epoxy Adhesive 84-1LMI	0.00023	Silver (Ag)	7440-22-4	80	0.00018	730		
			Epoxy Resin	Trade Secret	15	0.00003	137		
			Misc.	-	5	0.00001	46		
Wire	Pd doped Gold	0.00028	Gold (Au)	7440-57-5	99	0.00028	1116		
			Palladium (Pd)	7440-05-3	1	0.000003	11		
Lead Finish	Tin	0.01266	Tin (Sn)	7440-31-5	99.99	0.01266	50256		
			Misc.	-	0.01	0.000001	5		
Encapsulation	G600	0.10319	Silica Fused	60676-86-0	87.7	0.09049	359268		
			Phenol Resin	Trade Secret	5	0.00516	20483		
			Epoxy Resin	Trade Secret	5	0.00516	20483		
			Epoxy, Cresol Novolac	29690-82-2	2	0.00206	8193		
			Carbon Black	1333-86-4	0.3	0.00031	1229		

Total package weight (g) 0.25189

Comments

- Composition derived from MSDS and material CoC from vendors
- Component weight based on assembly of generic parts
- Reliability qualification reports are available upon request through the appropriate sales or marketing contact
- Third party testing for RoHS substances are available upon request to environment@melexis.com

Disclaimer

"MELEXIS has taken every effort to ensure that the information provided in this document is correct, accurate and up-to-date.

MELEXIS, however, shall not be held liable for any improper or incorrect use of the information described and/or contained herein and assumes no responsibility whatsoever for recipient's or a third party's use of this information. In no event MELEXIS shall be held liable for any direct, indirect, incidental, special, exemplary, or consequential damages (including, but not limited to: procurement of substitute goods or services; loss of use, data, or profits; or business interruption) however caused and on any theory of liability, whether in contract, strict liability, tort (including negligence or otherwise), or any other theory arising in any way out of the use of this system, even if advised of the possibility of such damage.

This disclaimer of liability applies to any damages or injury, whether based on alleged breach of contract, tortious behavior, negligence or any other cause of action".

The content of this document is CONFIDENTIAL & PROPRIETARY. ALL Rights Reserved.